



Applicants:

WonSun Shin; DoSung Chun; SangHo Lee; SeonGoo Lee; Vincent

DiCaprio

Assignee:

Anam & Amkor (jointly)

Title:

SEMICONDUCTOR PACKAGE AND METHOD FOR

FABRICATING THE SAME

Serial No.:

09/574,541

Filed:

5/19/00

Examiner:

Not Yet Assigned

Group Art Unit:

Not Yet Assigned

Docket No.:

AB-975 US

San Jose, California September 20, 2000

BOX MISSING PARTS COMMISSIONER FOR PATENTS Washington, D.C. 20231

RESPONSE TO NOTICE TO FILE MISSING PARTS OF APPLICATION - FILING DATE GRANTED

Dear Sir:

675029 v1

In response to the "Notice to File Missing Parts of Application - Filing Date Granted" mailed by the United States Patent and Trademark Office on August 4, 2000, the following documents are enclosed to complete the filing of the above-identified patent application:

- Declaration signed in counterparts by inventors WonSun Shin, SangHo Lee, and SeonGoo Lee in compliance with 37 CFR 1.63;
- 2. Declaration signed in counterparts by inventor DoSusng Chun in compliance with 37 CFR 1.63; and
- 3. Copy of Notice to File Missing Parts of Application Filing Date Granted.

A declaration signed by the remaining inventor, Vincent DiCaprio, was filed with the application.

The United States Patent and Trademark Office is hereby authorized to charge the following fees to Deposit Account No. 19-2386:

1. Surcharge for filing declaration on a date later than the

\$130.00

filing date of the application.

TOTAL FEES:

\$ 130.00

The Commissioner is hereby authorized to charge any additional fees, which may be required, or credit any overpayment to Deposit Account No. 19-2386.

It is hereby respectfully submitted that the enclosed documents complete the filing of the above patent application and justify the filing date of May 19, 2000. Please telephone the undersigned at (408) 453-9200, if there are any questions. This form is being submitted in duplicate.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to Commissioner For Patents, Washington, D.C. 20231, on 2000.

Attorney for Applicant(s)

Date of Sig

Respectfully submitted,

James E. Parsons

Attorney for Applicant(s)

Reg. No. 34,691

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